

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	Method of Managing Wafer Defects
---------------------------	----------------------------------

Application Number :

Date :

First Named Applicant: Hung-En Tai

Attorney Docket Number: LKSP0051USA

TOTAL FEE AUTHORIZED \$ 810

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 7	0	1202	18	0
Independent Claims : 1	0	1201	88	0
Subtotal For Extra Claims Fees: \$ 0				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Deposit account number: 503105

Access Code: ****

Deposit name: North America Intellectual Property Corporation

Deposit authorized name: /WINSTON HSU/

Signature: /VAEB-JMXX-8III/

Date (YYYYMMDD):

2004-09-08

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.